

Title (en)

COMPOSITION AND METHOD FOR REDUCING COPPER OXIDE TO METALLIC COPPER

Title (de)

ZUSAMMENSETZUNG UND METHODE ZUM REDUZIEREN VON KUPFEROXID ZU KUPFERMETALL

Title (fr)

COMPOSITION ET PROCEDE PERMETTANT DE REDUIRE L'OXYDE DE CUIVRE EN CUIVRE METALLIQUE

Publication

EP 0979208 A1 20000216 (EN)

Application

EP 98908643 A 19980220

Priority

US 9803406 W 19980220

Abstract (en)

[origin: CA2254362A1] A composition for reducing a copper oxide layer to metallic copper so as to facilitate bonding a resin to the metallic copper is disclosed. The composition is an aqueous reducing solution containing a cyclic borane compound. Examples of such cyclic borane compounds include those having nitrogen or sulfur as a ringforming member, such as morpholine borane, piperidine borane, pyridine borane, piperazine borane, 2,6-lutidine borane, 4-methylmorpholine borane, and 1,4-oxathiane borane, and also N,N-diethylaniline borane.

IPC 1-7

C01B 6/06; B05D 5/00; B05D 3/00

IPC 8 full level

C07D 295/02 (2006.01); **B05D 3/00** (2006.01); **B05D 5/00** (2006.01); **C01B 6/06** (2006.01); **C07D 213/18** (2006.01); **C07D 327/06** (2006.01); **C07F 5/02** (2006.01); **C22B 5/00** (2006.01); **C22B 15/00** (2006.01); **C23C 22/63** (2006.01); **C23C 22/83** (2006.01); **C23F 3/00** (2006.01); **C23G 1/20** (2006.01); **H05K 3/38** (2006.01)

CPC (source: KR)

C01B 6/06 (2013.01)

Designated contracting state (EPC)

AT BE CH DE ES FI FR GB IT LI NL SE

DOCDB simple family (publication)

CA 2254362 A1 19990820; CA 2254362 C 20040601; EP 0979208 A1 20000216; EP 0979208 A4 20001025; JP 2001527503 A 20011225; JP 3718722 B2 20051124; KR 100369489 B1 20030410; KR 20000065234 A 20001106

DOCDB simple family (application)

CA 2254362 A 19980220; EP 98908643 A 19980220; JP 55034098 A 19980220; KR 19980710168 A 19981211